



Special Issue on Engineering Failure Analysis

Call for Papers

Failure analysis is the process of collecting and analyzing data to determine the cause of a failure, often with the goal of determining corrective actions or liability. failure analysis can save money, lives, and resources if done correctly and acted upon. It is an important discipline in many branches of manufacturing industry, such as the electronics industry, where it is a vital tool used in the development of new products and for the improvement of existing products. The goal of this special issue is to provide a platform for scientists and academics all over the world to promote, share and discuss various new issues and developments in **engineering failure analysis**.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore **engineering failure analysis**. In this special issue, potential topics include, but are not limited to:

- Failure and reliability
- Failure of failure analysis
- Component analysis of failure parts
- Mechanical property test of failure parts
- Composition phase analysis of failure parts
- Methods of analysis

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue - Engineering Failure Analysis**” should be selected during your submission.

Special Issue timetable:

Submission Deadline	June 16th, 2024
Publication Date	August 2024

Guest Editor:

For further questions or inquiries

Please contact the Editorial Assistant at

eng@scirp.org